

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Title::	Low Cost, High Performance Flip Chip Package Structure
Attorney Docket Number::	CPAC 1015-1
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	
Total Drawing Sheets::	
Small Entity?::	No

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	US
Status::	Full Capacity
Given Name::	Rajendra
Middle Name::	J.
Family Name::	Pendse
Name Suffix::	
City of Residence::	Fremont
State or Province of Residence::	CA
Country of Residence::	US
Street of mailing address::	5245 Diamond Common
City of mailing address::	Fremont
State or Province of mailing address::	CA
Country of mailing address::	US

Postal or Zip Code of mailing address:: 94555

Correspondence Information

Correspondence Customer Number:: 22470

Representative Information

Representative Customer Number::	22470	
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Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Continuation-in-part-of	10084787	02/25/02
10084787	An application claiming the benefit under 35 USC 119(e)	60272236	02/27/01

Assignee Information

Assignee name:: ChipPAC, Inc
Street of mailing address:: 47400 Kato Road
City of mailing address:: Fremont
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94538